L Number	Hits	Search Text	DB	Time stamp
1	6	((((257/635,700,758).CCLS.) or	USPAT;	2003/04/11 08:40
,		((257/211,266,324).CCLS.)) and ((first adj	US-PGPUB;	
		wiring and second adj wiring) near layer)) and electrode and (multi-chip or multichip	EPO; JPO; DERWENT;	
		or multi near chip)	IBM TDB	
2	2	("6274404").PN.	USPAT;	2003/04/11 08:01
-	~	02.1101) 12111	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
3	2	("6403463").PN.	USPAT;	2003/04/11 08:01
			US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM TDB	
4	1	((first adj wiring and second adj wiring)	USPAT;	2003/04/11 08:44
		near layer) and electrode and (multi-chip	US-PGPUB;	
		or multichip or multi near chip) and	EPO; JPO;	
		conductive with bus	DERWENT;	
_			IBM_TDB	0000/04/11 00 14
6	0	(((first adj wiring and second adj wiring)	USPAT;	2003/04/11 08:44
i		near layer) and electrode and (multi-chip or multichip or multi near chip)and	US-PGPUB; EPO; JPO;	i
:		conductive near5 bus) not (((first adj	DERWENT;	
İ		wiring and second adj wiring) near layer)	IBM TDB	į
İ		and electrode and (multi-chip or multichip		
		or multi near chip) and conductive with		
		bus)		
5	1	((first adj wiring and second adj wiring)	USPAT;	2003/04/11 09:17
		near layer) and electrode and (multi-chip	US-PGPUB;	
		or multichip or multi near chip)and conductive near5 bus	EPO; JPO; DERWENT;	
		Conductive hears bus	IBM TDB	1
7 İ	16	electrode and (multi-chip or multichip or	USPAT;	2003/04/11 09:17
	2.0	multi near chip) and conductive near5 bus	US-PGPUB;	
		•	EPO; JPO;	
			DERWENT;	
	0.640	4055 4605 F00 F50 067 0	IBM_TDB	0000/04/10 14 56
-	3648	(257/635,700,758).CCLS.	USPAT; US-PGPUB;	2003/04/10 14:56
			EPO; JPO;	
			DERWENT;	
			IBM TDB	1
-	1274	(257/211,266,324).CCLS.		2003/04/10 12:53
			US-PGPUB;	
1			EPO; JPO;	; !
			DERWENT;	
	2041	//20/110 622\ CCTC	IBM_TDB	2003/04/10 12:52
-	2641	(438/118,622).CCLS.	USPAT; US-PGPUB;	2003/04/10 12:53
			EPO; JPO;	
			DERWENT;	1
			IBM_TDB	
-	3086	(438/128,129,216,261,591,593).CCLS.	USPĀT;	2003/04/10 12:54
			US-PGPUB;	
		-	EPO; JPO;	
,			DERWENT;	
_	4	'multiple-chip' and	IBM_TDB USPAT;	2003/04/10 12:57
1	ч	((257/635,700,758).CCLS.)	US-PGPUB;	2000/04/10 12:0/
		,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	EPO; JPO;	
			DERWENT;	r F
1			IBM_TDB	1
-	0	'multiple-chip' and	USPAT;	2003/04/10 12:57
		((257/211,266,324).CCLS.)	US-PGPUB;	
			EPO; JPO;	
1			DERWENT;	
			IBM_TDB	

-	0	'multiple-chip' and ((438/118,622).CCLS.)	USPAT;	2003/04/10 12:57
			US-PGPUB; EPO; JPO;	
		,	DERWENT;	
			IBM_TDB	
-	0		USPAT;	2003/04/10 12:57
		((438/128,129,216,261,591,593).CCLS.)	US-PGPUB;	
			EPO; JPO; DERWENT;	
	,		IBM TDB	i i
-	224	'multiple-chip'	USPĀT;	2003/04/10 14:10
			US-PGPUB;	
-			EPO; JPO; DERWENT;	
			IBM TDB	
_	1444	stack\$3 near chip	USPAT;	2003/04/10 14:11
			US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM TDB	
_	22	(stack\$3 near chip) and	USPAT;	2003/04/10 14:12
		((257/635,700,758).CCLS.)	US-PGPUB;	
			EPO; JPO;	
		"	DERWENT;	
_	2	(stack\$3 near chip) and	IBM_TDB USPAT;	2003/04/10 14:32
		((257/211, 266, 324).CCLS.)	US-PGPUB;	2000,01,10 14.02
			EPO; JPO;	
			DERWENT;	
_	3	(stack\$3 near chip) and	<pre>IBM_TDB USPAT;</pre>	2003/04/10 14:33
_	3	((438/128,129,216,261,591,593).CCLS.)	US-PGPUB;	2003/04/10 14:33
		(1.10, 1.00,	EPO; JPO;	
			DERWENT;	1
	30	/-h162	IBM TDB	2002/04/20 24 55
_	32	(stack\$3 near chip) and ((438/118,622).CCLS.)	USPAT; US-PGPUB;	2003/04/10 14:55
		(((300/110,022).0010.)	EPO; JPO;	
	-		DERWENT;	
		(05D (505 D00 D50)	IBM_TDB	
-	3648	(257/635,700,758).CCLS.	USPAT;	2003/04/10 14:56
			US-PGPUB; EPO; JPO;	
	de la companya de la		DERWENT;	
			IBM_TDB	
-	2	("5892276").PN.	USPAT;	2003/04/10 14:59
			US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	2	("5939790").PN.	USPAT;	2003/04/10 15:27
			US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
_	130	((257/635,700,758).CCLS.) and	USPĀT;	2003/04/10 16:08
		((257/211,266,324).CCLS.)	US-PGPUB;	•
	!		EPO; JPO;	
			DERWENT; IBM TDB	;
_	4792	((257/635,700,758).CCLS.) or	USPAT;	2003/04/10 16:08
		((257/211,266,324).CCLS.)	US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM TDB	
_	888	(((257/635,700,758).CCLS.) or	USPAT;	2003/04/10 16:09
		((257/211,266,324).CCLS.)) and	US-PGPUB;	
		('multi-chip' chips (stack\$3 near chip))	EPO; JPO;	1
		-	DERWENT;	
Ĺ	<u> </u>		IBM TDB	

-	5355	first adj wiring and second adj wiring	USPAT;	2003/04/10 16:10
}	1		US-PGPUB;	:
	i		EPO; JPO;	1
	İ		DERWENT;	
			IBM_TDB	
-	2275	(first adj wiring and second adj wiring)	USPAT;	2003/04/10 16:11
		near layer	US-PGPUB;	
1			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	189	(((257/635,700,758).CCLS.) or	USPAT;	2003/04/10 16:11
		((257/211,266,324).CCLS.)) and ((first adj	US-PGPUB;	
	1	wiring and second adj wiring) near layer)	EPO; JPO;	1
			DERWENT;	į
			IBM_TDB	
-	98	(((,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	USPAT;	2003/04/11 07:29
		((257/211,266,324).CCLS.)) and ((first adj	US-PGPUB;	
		wiring and second adj wiring) near layer))	EPO; JPO;	
		and electrode	DERWENT;	
			IBM_TDB	